Attorney Docket: 42.P16002 Express Mail No.: EV320119206US

ABSTRACT OF THE DISCLOSURE

[0061] A variable temperature and/or reactant dose atomic layer deposition (VTD-ALD) process modulates ALD reactor conditions (e.g., temperature, flow rates, etc.) during growth of a film (e.g., metallic) on a wafer to produce different film properties a different film depths.